SDD from device modeling to mass production - practical experience





Outline

- -Motivations ALICE at LHC
- -ITS&SDD system
- From specs to detector
 - -HV divider & stability
 - -Injectors & speed variations
 - -NTD fluctuations
 - -Radiation damage
- -Mass production first results

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Overall view of the LHC experiments.

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311511515)

collisions PbPb at 1150 TeV = 0.18 mJ

CERN

Point 1

ALICE Point 2

LHC - B

Point 8





THE EXPERIMENT IS A CONDENSATE OF CUTTING EDGE TECHNOLOGIES

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The SDD collaboration

- INFN Torino Italy
- INFN Trieste Italy
- INFN Bologna Italy
- INFN Roma Italy
- INFN Alessandria- Italy
- Ohio State University Columbus Ohio USA
- University of Jyvaskyla Jyvaskyla Finland
- Nat. Acad. of Sciences, Bogolyubov Inst. for Th. Phys. Kiev Ukraine
- Scientific Res. Techn. Inst. of Instrument Making Kharkov Ukraine
- Acad. of Sciences of Czech Republic Rez U Prahy Czech Republic
- St. Petersburg State University St. Petersburg Russia

Silicon Drift Detectors

Tot. No. channels $133 \cdot 10^3$ Tot. No. detectors 260 total area

 1.31 m^2

• 6 Layers, three technologies (keep occupancy ~constant ~2%)

- Silicon Pixels (0.2 m², 9.8 M channels)
- Silicon Drift (1.3 m², 133 k channels)
- Double-sided Strip (4.9 m², 2.6 M channels)



 $L_{out} = 97.6 \text{ cm}$

 R_{out} =43.6 cm

Layer 4

23.8

22

8

Layer 3

14.9

14

6

Radius (mm)

Ladders

SDDs per

ladder

Two dimentional information no ambiguities

20 0 5

The silicon drift detector (SDD)





The silicon drift detector will equip two consecutive barrels for a total sensitive area of 1.1 m²

- The presented design points towards :
 - totally self supported on board high voltage divider,
 - injectors
 - high stability in the detector's performances
 - redundant design able to allow a satisfactory production yield.
 - the ability of the detector's design to withstand, with minimal consequences, the occurrence of a defect
 - control the effects of thermal dissipation and gradients across the sensitive area
 - resist to the foreseen dose in case of accelerator beam losses,
 - Contain and minimize NTD residual Doping fluctuations effects

Silicon Drift Detector



- Wafer: 5" Neutron Transmutation Doped <111> 3 k Ω .cm, 300 μ m thick
- Area: sensitive: 7.02×7.53 cm², divided into two drift regions total $: 7.25 \times 8.76 \text{ cm}^2$, (ratio = 0.81)
- Each drift region:

35 mm long 290 cathodes driven by built-in voltage divider 256 anodes – 294 µm pitch **3 rows of 33 MOS charge injectors** (v_{drift} calibration)

Guard regions:

independent built-in voltage dividers

- > Typical operating parameters: Drift bias voltage: -2.4 kV, 8V/cathode E=670V/cm Maximum drift time : 4.3 μ s, $v_d = 8 \mu m/ns$
- Power dissipation on board: 1.13 W
 - **Rtot equivalent of the all drift + guard dividers (kohm)** 4781
 - Total current in all dividers, from Rtot equivalent (mA) 0.49
 - **P** tot (W)

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- \blacktriangleright Production yield: > 65%
 - dedicated double sided process
 - Redundant design
 - Separated guard and drift dividers



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Performance of the divider





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(1) Short





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(2) High current centre





Measurement

b)

120

 $V_{BIAS} = -1200 V$

125 130 135 140

meta' rivelatore con difetto meta' rivelatore senza difetto

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120 125 130 135 140 145 150 155 160 165 170

catodo (/#)

20 0 5

155 160 165

150

145

catodo (/#)



(2) High current centre







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On board divider at -2400V



Voltage drop every 10 drift cathodes

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Integrated divider



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Detector design features





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Point like Injectors







anodes

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Temperature gradient and drift time as seen by the first line of injectors. The centre to edge induced delay is Approximately 80-100 ns



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Beam Test - Setup



PS / SPS π,p (up to 375 GeV/c)



Two Front-end PCB's, with the same layout as the hybrid, connected to an SDD for the August 03 beam test



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SDD front-end electronics



Beam test of SDD with PASCAL-32 & AMBRA-2 (first results) ADC's running at 20MHz - some missing codes at 40MHz

Design specifications

- dynamic range: up to 8 MIPs
- noise: 250 e⁻
- readout time < 1ms
- power consumption: <5 mW/channel
- chips thinned to 300µm



PASCAL (64 channels)

- > Preamplifier ($\tau \sim 40$ ns, RC-CR² shaping)
- Analog memory (64 ×256 cells)
- ➤ 32 10-bit linear ADC (1 every 2 channels)
- **AMBRA** (64 channels)
- Four 16 kB buffers
- > 10 to 8-bit compression

SDD front-end electronics



Beam test of SDD with PASCAL-32 & AMBRA-2



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Parasitic Electrostatic Field,







FIGURE 6. Systematic deviations (gray scale in μm) of the anode coordinate (a) and the drift coordinate (b) of the electron cloud with respect to the reference position of the crossing point of the particle coordinate, as a function of the anodic coordinate x and the drift distance y. Component of the parasitic electric field (V/cm) perpendicular to the drift axis (c) and parallel to the drift axis (d) induced by doping fluctuations as a function of the anodic coordinate X, and the drift distance Y.

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Spatial Resolution





FIGURE 7. Drift axis (light circles) and anode axis (dark circles) spatial resolution of the ALICE SDD as function of the drift distance, after the correction of the doping inhomogeneities.

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Performance from beam test (2)





Double track resolution compared with simulations

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Performance from beam test (3) Drift velocity calibration



Drift time of 4 MOS injectors during 24 hours

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Irradiation tests

At the **LINAC** of the **ELETTRA** synchrotron in Trieste.

expected in ALICE

Layer	Dose (krad)	neutron Flux (x 10 ¹¹ cm ⁻²)
SDD 1	13.4	3.5
SDD 2	5.4	3.3



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whole surface





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only the central area





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SDD test systems with 2-sided probe stations





ALICE Silicon Drift Detector



Wafer: 5", Neutron Transmutation Doped (NTD) silicon, $3 \text{ k}\Omega \cdot \text{cm}$ resistivity, 300 µm thickness Active area: 7.02×7.53 cm² (83% to total)

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72.5-

70.0-

0

50



UP-half



.....

150

200

100

.

250

Date: 25/10/200



DOWN-half



Voltage drop between 10 consecutive drift cathodes (V)





UP-half



SDD readout architecture (each half-ladder)







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Layout of an SDD module with its microcables





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Drift detectors



Features:

•X – Y Position information •High count rate • Large area detectors •High X-ray resolution



Largest drift detector in the world ≻Active area: 52 cm2 ≻Anode pitch: 294µm ≻512 anodes on two rows ➢Position resolution: <50µm</p> >MOS injectors for calibration

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H Drift strips > Anode 9 Guard strips > Example of a 11 mm² oblong area drift detector for X-Ray with the anode on side

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Design of large drift detector

200 mm² area – one linear anode in the middle4 detectors can be mounted in one housing



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Design of large "pixel-drift" detector

24 x 37.5 mm² = 900 mm² area – one linear anode in each "pixel-drift"



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Based on the established structures design à la carte drift detectors







Linear drift detector – 40 mm2

10 mm2 X- Ray detector with anode on chip side

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12 x 2 mm2 rectangular drift detector with central anode

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Fig. 6. ²⁴¹Am spectrum at $T = -20^{\circ}$ C, with a shaping time of 2 µs and a drift field of 110 V/cm (see text for the FWHM resolutions).



Fig. 7. Linearity plot obtained by fitting all experimental points.

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Fig. 3. Picture of the detector mounted in the test board, housing also the front-end preamplifier.





Fig. 4. Semilog plot of the measured anode currents as a function of the applied bias voltage for different temperatures.

Also, at higher temperatures the results remain good; for example, at $T = -15^{\circ}$ C we have for the

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Fig. 5. Spectrum of ⁵⁵Fe (5.9 keV) obtained at $T = -20^{\circ}$ C, with a shaping time of 2 µs and a drift field of 110 V/cm (FWHM = 1.9 keV).

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Conclusions

Satisfactory detector spatial resolution:

- along drift axis: 30-35 μm
- along anodic axis: better than 30 µm over 90% of the detector

Doping fluctuations :

- NTD silicon custom development
- Laser mapping of the detector

The detector after Alice like irradiation:

- **Anodic current remains within acceptable limits**
- **L** the potential distribution is altered by the highier current,
- **L**requires drift speed calibration

No defect propagation at Vbias for: short up to <u>5 cathodes</u>
up to <u>1 µA</u> di corrente generation center
<u>divider interruption</u>





V. Bonvicini et al. / Nuclear Instruments and Methods in Physics Research A 439 (2000) 471–475

Fig. 2. Schematic view of high-voltage divider-drift electrode implantation on n- and p-side. The two implants are shown shifted only for the sake of clarity, but in reality they are perfectly overlapped.

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